ADVANCED POWER **TECHNOLOGY**

APT6017JLL

600V 31A 0.170Ω

POWER MOS 7™

Power MOS 7[™] is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7™ by significantly lowering R_{DS(ON)} and Q_a. Power MOS 7[™] combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.



Increased Power Dissipation

Lower Miller Capacitance

Easier To Drive

Lower Gate Charge, Qg

Popular SOT-227 Package





MAXIMUM RATINGS

All Ratings: $T_C = 25^{\circ}$ C unless otherwise specified.

Symbol	Parameter	APT6017JLL	UNIT	
V _{DSS}	Drain-Source Voltage	600	Volts	
I _D	Continuous Drain Current @ T _C = 25°C	31	Amno	
I _{DM}	Pulsed Drain Current ①	124	Amps	
V _{GS}	Gate-Source Voltage Continuous	±30		
V _{GSM}	Gate-Source Voltage Transient	±40	Volts	
P _D	Total Power Dissipation @ T _C = 25°C	375	Watts	
' D	Linear Derating Factor	3.0	W/°C	
T_J , T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C	
T _L	Lead Temperature: 0.063" from Case for 10 Sec.	300		
I _{AR}	Avalanche Current (Repetitive and Non-Repetitive)	31	Amps	
E _{AR}	Repetitive Avalanche Energy ①	35	ml	
E _{AS}	Single Pulse Avalanche Energy 4	1600	mJ	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage (V _{GS} = 0V, I _D = 250μA)	600			Volts
I _{D(on)}	On State Drain Current $@$ ($V_{DS} > I_{D(on)} \times R_{DS(on)} Max, V_{GS} = 10V$)	31			Amps
R _{DS(on)}	Drain-Source On-State Resistance ② (V _{GS} = 10V, 0.5 I _{D[Cont.]})			0.170	Ohms
I _{DSS}	Zero Gate Voltage Drain Current (V _{DS} = V _{DSS} , V _{GS} = 0V)			100	μΑ
	Zero Gate Voltage Drain Current $(V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_{C} = 125^{\circ}C)$			500	
I _{GSS}	Gate-Source Leakage Current (V _{GS} = ±30V, V _{DS} = 0V)			±100	nA
V _{GS(th)}	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 5mA)$	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - http://www.advancedpower.com

FAX: (541) 388-0364

USA

DYNAMIC CHARACTERISTICS

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Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V		4300		
C _{oss}	Output Capacitance	V _{DS} = 25V		760		pF
C _{rss}	Reverse Transfer Capacitance	f = 1 MHz		48		
Q_g	Total Gate Charge ^③	V _{GS} = 10V		99		
Q _{gs}	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		23		nC
Q_{gd}	Gate-Drain ("Miller") Charge	$I_{D} = I_{D[Cont.]} @ 25^{\circ}C$		44		
t _{d(on)}	Turn-on Delay Time	V _{GS} = 15V		13		
t _r	Rise Time	$V_{DD} = 0.5 V_{DSS}$		10		ns
t _{d(off)}	Turn-off Delay Time	$I_{D} = I_{D[Cont.]} @ 25^{\circ}C$		29		113
t _f	Fall Time	$R_G = 0.6\Omega$		7		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

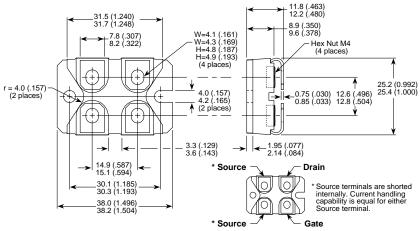
Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I _s	Continuous Source Current (Body Diode)			31	A
I _{SM}	Pulsed Source Current (1) (Body Diode)			124	Amps
V _{SD}	Diode Forward Voltage ② (V _{GS} = 0V, I _S = -I _{D[Cont.]})			1.3	Volts
t _{rr}	Reverse Recovery Time $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		600		ns
Qrr	Reverse Recovery Charge $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		13.0		μC
dv/ _{dt}	Peak Diode Recovery dv/ _{dt} (5)			8	V/ns

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{ hetaJC}$	Junction to Case			0.33	°C/W
R_{\thetaJA}	Junction to Ambient			40	C/VV

¹ Repetitive Rating: Pulse width limited by maximum junction temperature.

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters and (Inches)

² Pulse Test: Pulse width < 380 µs, Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

 $[\]textcircled{4}$ Starting T_j = +25°C, L = 3.33mH, R_G = 25 Ω , Peak I_L = 31A

⑤ dv/_{dt} numbers reflect the limitations of the test circuit rather than the device itself. $I_S \le -I_{D[Cont.]}$ divide itself.